

1    **ABSTRACT OF THE DISCLOSURE**

2           A functional PCB module in accordance with the present invention  
3    comprises a frame having at least one chip recess, at least one chip mounted in  
4    the chip recess, at least one printed circuit formed on one side of the frame and  
5    material filling the chip recess. The chip has terminals interconnected to the  
6    printed circuit. Since the chip is embedded in the frame to complete the  
7    functional PCB module, the functional PCB module is effectively thinner.  
8    Furthermore, two or more functional PCB modules are easily combined to form  
9    a multi-layer PCB by using a vacuum compression process.